

(SiO<sub>2</sub>)

..  
/

(25

(W<sub>p</sub>=20 %)

(0.445 w/m.°c)

μm)

.(k=0.61 w/m.°c)

:

## The Effect of Weight Fraction and Grain Size of (SiO<sub>2</sub>) on the Thermal Conductivity of Epoxy

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### Abstract

This research deals with use of Lee's disc to measure the thermal conductivity and temperature change with respect to time through the thickness of the specimens of the unreinforced epoxy and reinforced epoxy by silica particles at different weight fraction and grain size. The results show that the thermal conductivity increased by increasing the weight fraction and reduced by increasing the grain size of silica particles by nonlinear relationship and the maximum difference between the unreinforced epoxy and reinforced epoxy was (0.445 W/m.°c) at weight fraction (20 %) and grain size (20 μm) of silica particles, where at this value of weight fraction and grain size the thermal conductivity was maximum value (k= 0.61 W/m.°c).

( - ) ( - )

[1].

[1].

:

[2].

[3].

Murthy

[3].

Khimov

[4].

(8 Gpa)

Linson & Stapley

( Al

[5] (75  $\mu$ m) )

Tin Klepaugh & Truesdale

4 2)

(100-1000C<sup>o</sup>)

(10).

[6] (99%)

Midttomme & Roaledset

[7]

1979 Philling

(80-270 K)

[8]

SiO<sub>2</sub>

(0.1 μm)

(1-15%)

(25-50 %)

(1 μm)

[10 & 9]

(K<sub>L</sub>)

(K<sub>u</sub>)

: [11]

$$K_u = K_p \cdot V_p + K_m \cdot V_m \quad (\text{W/m} \cdot ^\circ\text{C}) \quad (1)$$

$$K_L = \frac{K_p \cdot K_m}{K_p \cdot V_m + K_m \cdot V_p} \quad (\text{W/m} \cdot ^\circ\text{C}) \quad (2)$$

$$\begin{aligned} &: \\ &= K_p, K_m \\ &= V_p, V_m \end{aligned}$$

$$V_p = \frac{\rho_c}{\rho_p} \cdot W_p \cdot 100 \% \quad (3)$$

$$V_m = \frac{\rho_c}{\rho_m} \cdot W_m \cdot 100 \% \quad (4)$$

(g/cm<sup>3</sup>)

$$\begin{aligned} &: \\ &= \rho_m, \rho_p, \rho_c \\ &= W_m, W_p \end{aligned}$$

$$W_p + W_m = 1 \quad (5)$$

$$V_p + V_m = 1 \quad (6)$$

(Lee's disc )

(2,3) (0.2A) (6V)

( 5)

ds= 40 ) (4mm ) SiO<sub>2</sub>

( 25 μm , 75 μm and 125 μm) (Wp= 5, 10, 15, and 20 %) (mm

$$Q = -K \cdot \frac{dt}{dx} \quad (7)$$

(d=40mm) (d<sub>s</sub>=12mm)  
 (Q)  
 (Thermal Flux) : Q  
 (Watt / m<sup>2</sup>)  
 (W / m . °C) : K  
 (°C / m) :  $\frac{dT}{dX}$   
 : [12] ( & )

$$K \cdot \left[ \frac{T_2 - T_1}{d_s} \right] = e \cdot \left[ T_1 + \frac{2}{r} \cdot \left( d_1 + \frac{1}{2} d_s \right) \cdot T_1 + \frac{1}{r} \cdot d_s \cdot T_2 \right] \quad (8)$$

(m<sup>2</sup>) ( ) : e  
 (m) : d<sub>1</sub>, d<sub>2</sub>, d<sub>3</sub>  
 (m) : ds  
 (m) : r  
 (°C) : T<sub>1</sub>, T<sub>2</sub>

(9) (e)

-:[13]

$$I \cdot V = \pi \cdot r^2 \cdot e \cdot (T_1 + T_3) + 2 \cdot \pi \cdot r \cdot e \cdot \left[ d_1 \cdot T_1 + \frac{1}{2} \cdot d_s \cdot (T_1 + T_2) + d_2 \cdot T_2 + d_3 \cdot T_3 \right] \quad (9)$$

-:

:T<sub>3</sub> (°C)  
 :i (Amper)  
 :v (Volt)

(T<sub>1</sub> & T<sub>2</sub>) ( )  
 (125 μm) (W<sub>p</sub>= 10 %) (W<sub>p</sub>= 20 %)  
 (25 μm)  
 (T<sub>2</sub>) (T<sub>1</sub>)  
 (T<sub>1</sub>) (T<sub>2</sub>) (T<sub>1</sub>) (T<sub>2</sub>)  
 (W<sub>p</sub>= 20) (25 μm) %  
 ( )  
 (125 μm, & 75 μm, 25 μm)  
 (0.445 W/m. °c) (25 μm) (20 %)  
 (20 %) (0.165 W/m. °c) (125 μm)

( )  
 (W<sub>p</sub>=20 %) (W<sub>p</sub>=5 %)

$(k=0.61 \text{ w/m.}^\circ\text{c})$  $(W_p=20 \%)$  $(25 \mu\text{m})$  $(W_p= 20 \%)$  $(W_p= 5 \%)$ 

:

 $(T_2 \& T_1)$ 

(-

(-

 $(w_p=20$  $(25 \mu\text{m})$  $(k=0.61 \text{ w/m.}^\circ\text{c})$ 

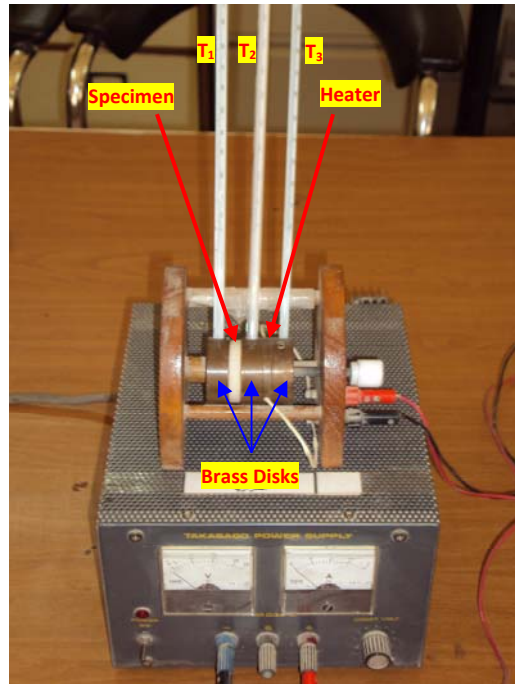
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 $(0.455 \text{ w/m.}^\circ\text{c})$ 

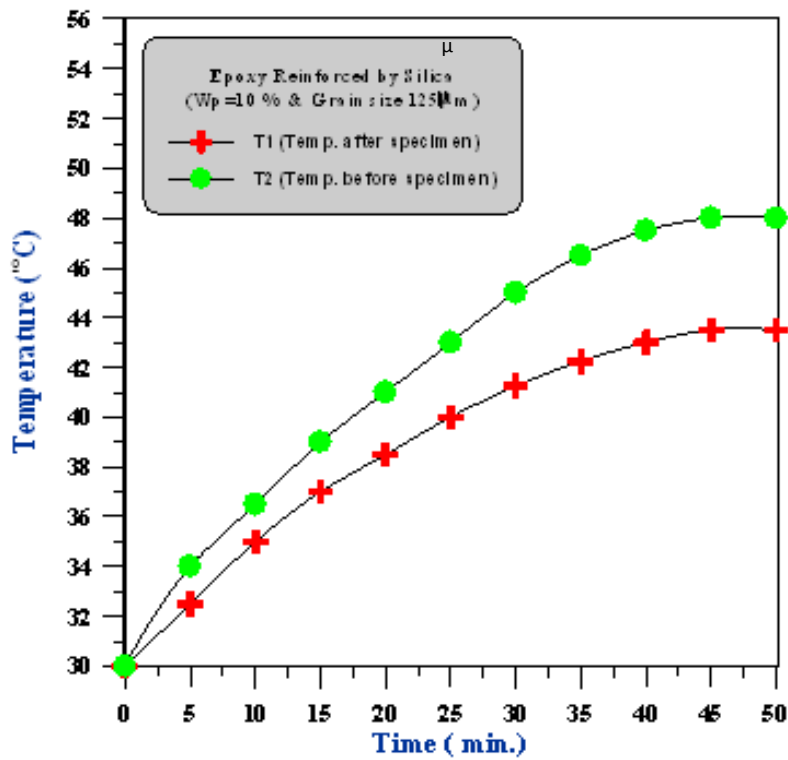
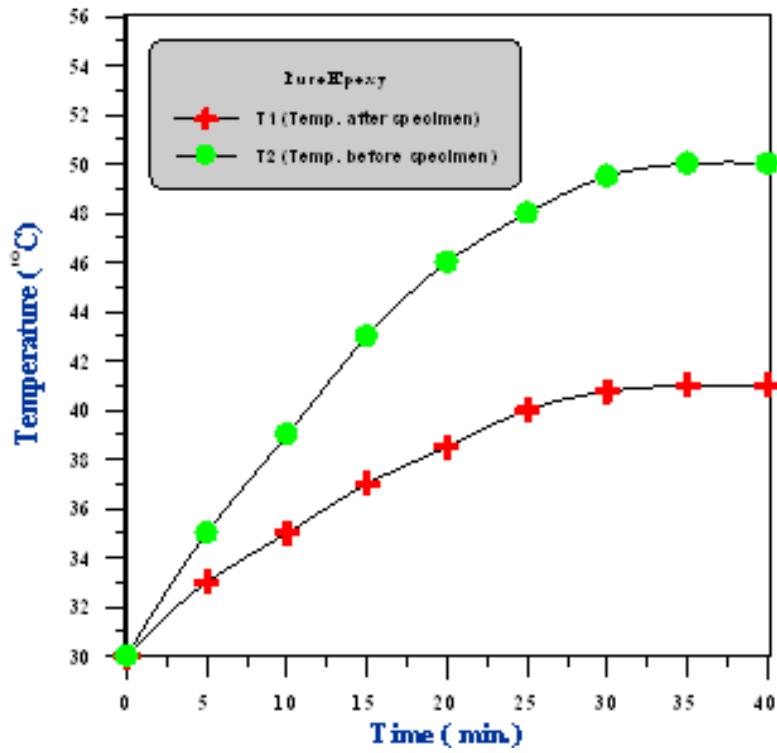
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- [1]W. Bolton," Engineering Materials Technology", butterworth – Heinemann, Third edition, (1998).
- [2]Rymond B. Seymor," Polymer Composites", the Netherland First Edition, (1990).
- [3]BSR Murthy, Dr.A. Rama Krishna and B.V. Rama Krishna," Thermal Analysis of Epoxy Based Fiber-Reinforced", IE(I) Journal-MC, Vol.84, April, (2004).
- [4]E.A.Ekimov, N.V. Suetin, A.F Popovich," Effect of Microstructure and grain size on the thermal conductivity of high pressure sintered diamond composites", J. Inorganic Materials, Vol.44, No.3 (2008).
- [5]W.J. Tamlinan and D. Stapley,"Thermal Conductivity of epoxy resin Aluminium", Journal of Materials Science, Vol. 12, No.8 (2004).
- [6]Tin Ylepaugh, J.R. & Truesdale, R.S.,"Grain Size Effects on the Thermal Conductivity of Ceramic Oxides", (2010).
- [7]Kirsti Midttomme and Elen Roaldset, " The Effect of Grain Size on Thermal Conductivity of Quartz sands and silts", Vol.4, No.2, May (1998).
- [8]M.W. Pilling, B. Yates, M.A. Black,"The Thermal Conductivity of Carbon Fiber – Reinforced Composites ", Journal of Materials Science, Vol.14, (1979).
- [9]G.Lublin,"Handbook of Fiber glass and Advanced Composite", Littone Educational Co. Network, (1960).

- [10]William D. Callister,"Materials Science and Engineering An Introduction", Sixth Edition, John Wiley and Sons, Inc., (2003).
- [11]R.M.Jones,"Mechanics of Composite Materials", Mc Graw-Hill, New York, (1975).
- [12]L. Holliday,"Composite Materials", Elsevier Publishing, London, (1966).
- [13]L.J. Broutman and R.H. Krock,"Modern Composite Materials", Eddison Wisely, London, (1967).

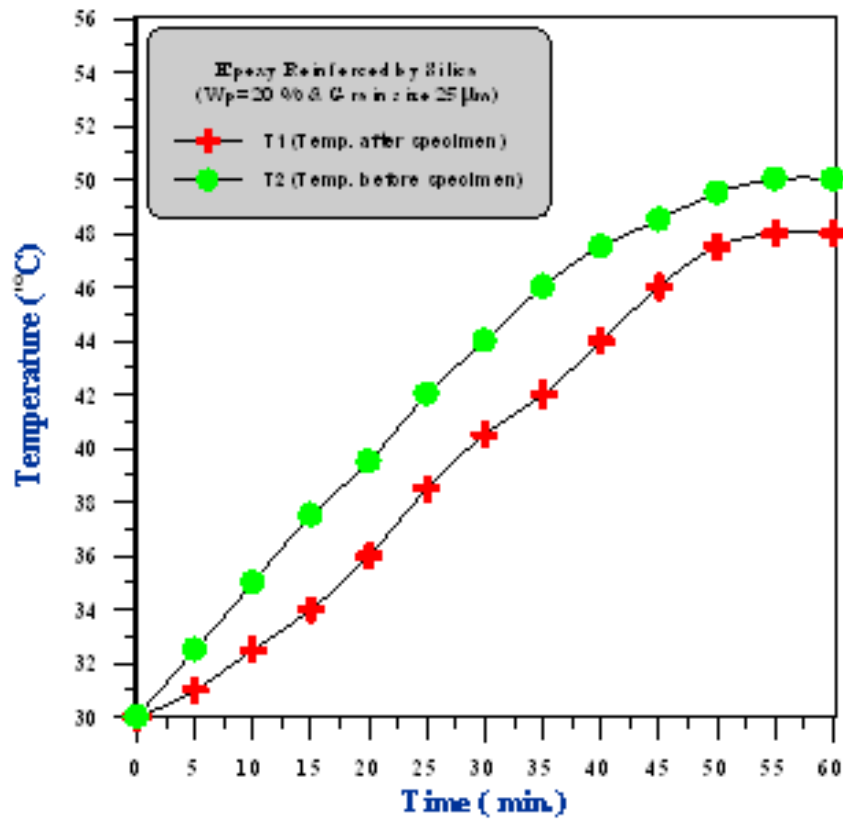






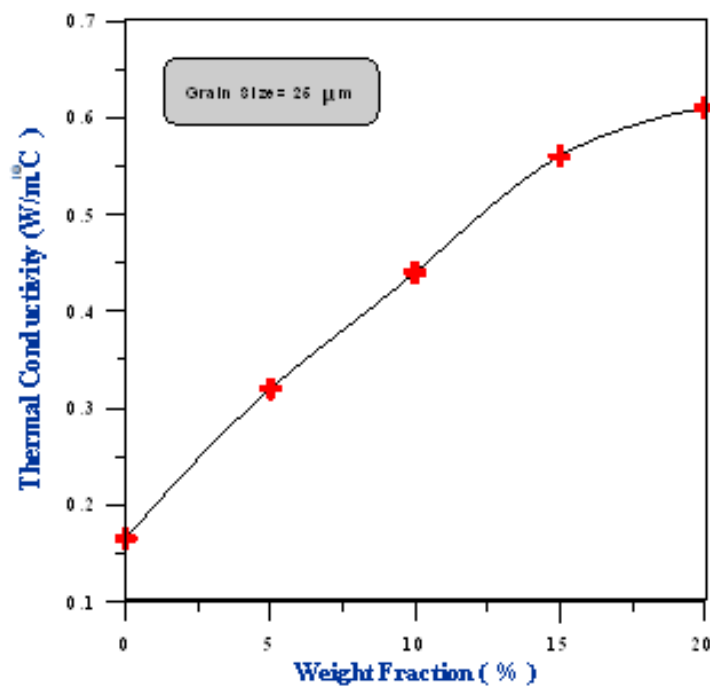
(Wp=10 %)

. (125 μm)

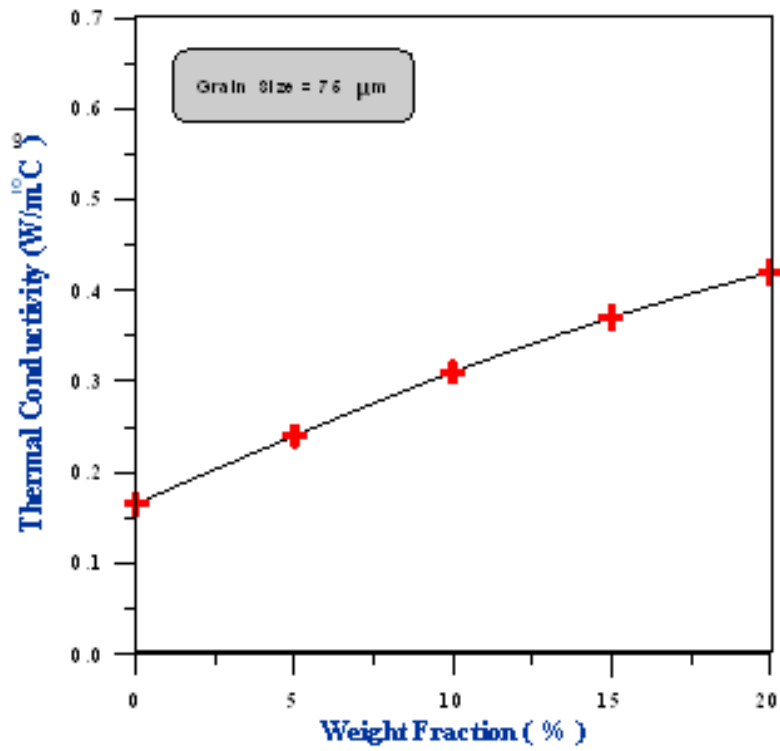


( $W_p=20\%$ )

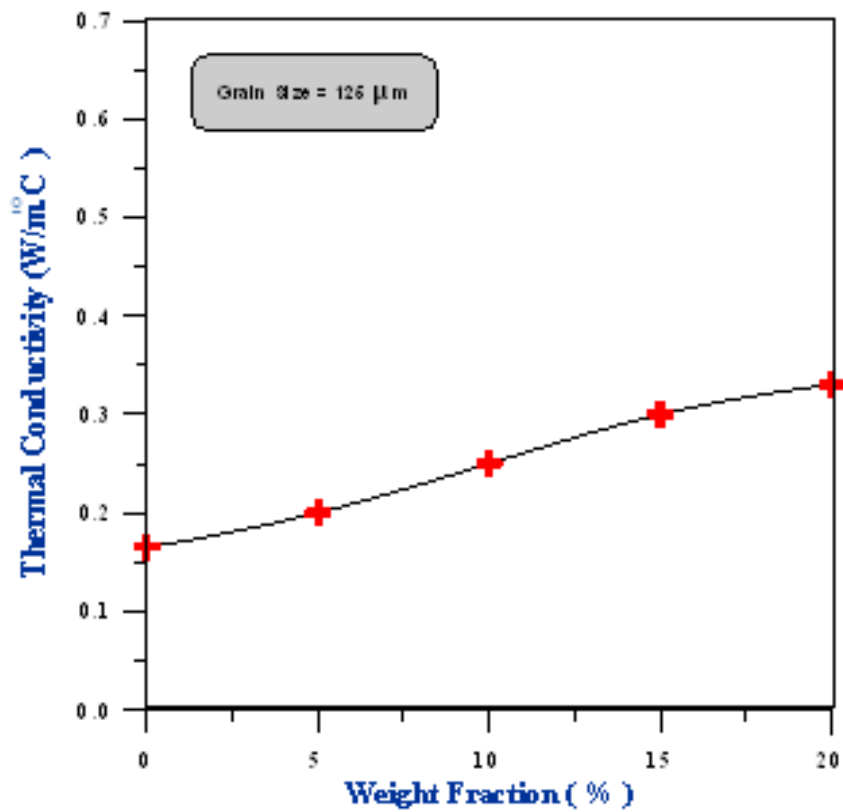
. ( $25\ \mu m$ )



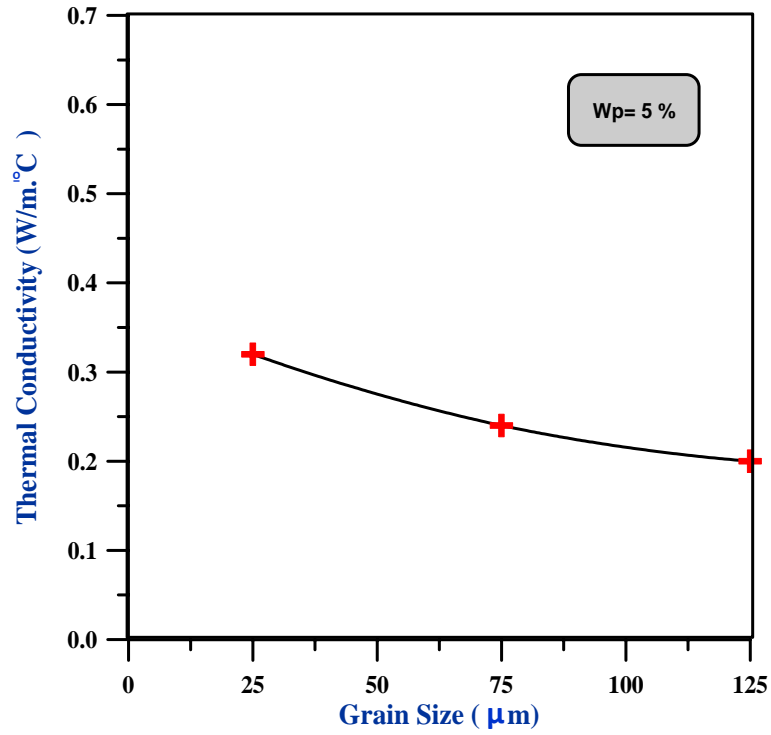
. ( $25\ \mu m$ )



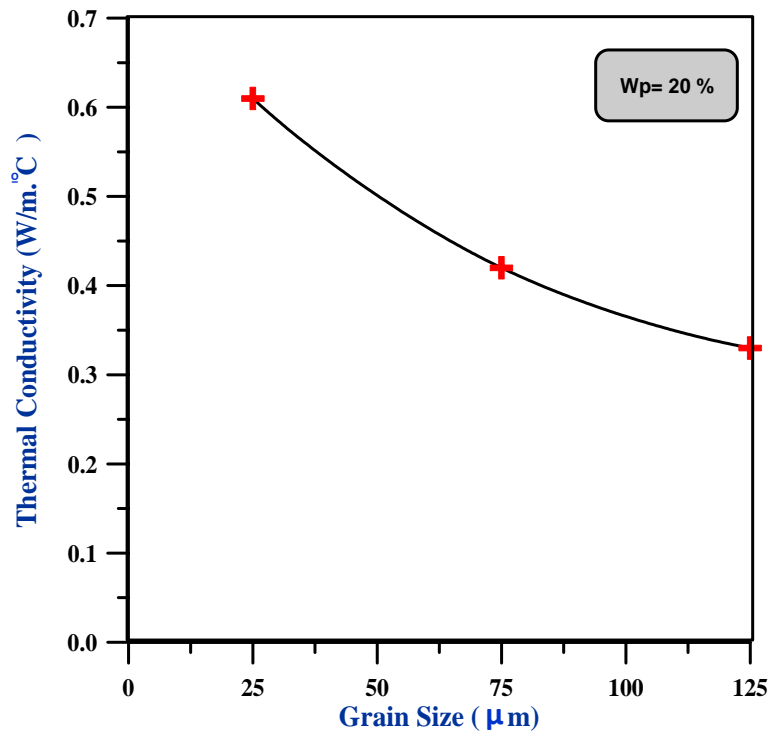
. (75  $\mu\text{m}$ )



. (125  $\mu\text{m}$ )



( $W_p = 5\%$ )



( $W_p = 20\%$ )